

RELIABILITY REPORT  
FOR  
MAX1482CSD+T  
PLASTIC ENCAPSULATED DEVICES

October 4, 2012

**MAXIM INTEGRATED**

160 RIO ROBLES  
SAN JOSE, CA 95134

<b>Approved by</b>
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## Conclusion

The MAX1482CSD+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX1482 and MAX1483 are low-power transceivers for RS-485 and RS-422 communication. Both feature slew-rate-limited drivers that minimize EMI and reduce reflections caused by improperly terminated cables. Data rates are guaranteed up to 250kbps. The MAX1482/MAX1483 draw only 20 $\mu$ A of supply current. Additionally, they have a low-current shutdown mode that consumes only 0.1 $\mu$ A. Both parts operate from a single +5V supply. Drivers are short-circuit current limited and are protected against excessive power dissipation by thermal shutdown circuitry that places the driver outputs into a high-impedance state. The receiver input has a fail-safe feature that guarantees a logic-high output if the input is open circuit. The MAX1482 is full duplex and the MAX1483 is half duplex. Both parts have a 1/8-unit-load input impedance that guarantees up to 256 transceivers on the bus.

## II. Manufacturing Information

A. Description/Function:	20 $\mu$ A, 1/8-Unit-Load, Slew-Rate-Limited, RS-485 Transceivers
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Thailand, Philippines
F. Date of Initial Production:	Pre 1997

## III. Packaging Information

A. Package Type:	14-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1901-0103
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	84°C/W
M. Multi Layer Theta Jc:	34°C/W

## IV. Die Information

A. Dimensions:	82 X 58 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)  
Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 240 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 4.6 \times 10^{-9}$$

$$\lambda = 4.6 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.04 @ 25C and 0.69 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing (ESD lot NGZABO001A D/C 9616, Latch-Up lot NGZABU018A D/C 9836)

The RS28 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX1482CSD+T**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C	DC Parameters	80	0	NGZABZ001B, D/C 9504
	Biased	& functionality	80	0	XGZAAY001A, D/C 9504
	Time = 192 hrs.		80	0	XGZBAY001A, D/C 9504

Note 1: Life Test Data may represent plastic DIP qualification lots.